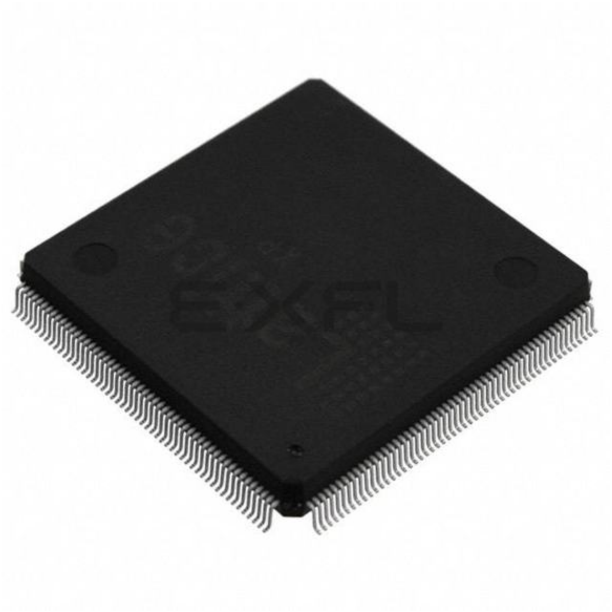

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6000
Total RAM Bits	73728
Number of I/O	142
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp6c-5qn208c

LatticeXP Family Data Sheet Introduction

July 2007 Data Sheet DS1001

Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - No external configuration memory
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through system configuration and JTAG ports
- **Sleep Mode**
  - Allows up to 1000x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **Extensive Density and Package Options**
  - 3.1K to 19.7K LUT4s
  - 62 to 340 I/Os
  - Density migration supported
- **Embedded and Distributed Memory**
  - 54 Kbits to 396 Kbits sysMEM™ Embedded Block RAM
  - Up to 79 Kbits distributed RAM
  - Flexible memory resources:
    - Distributed and block memory
- **Flexible I/O Buffer**
  - Programmable sysIO™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTL
    - SSTL 18 Class I
    - SSTL 3/2 Class I, II
    - HSTL15 Class I, III
    - HSTL 18 Class I, II, III
    - PCI
    - LVDS, Bus-LVDS, LVPECL, RSDS
- **Dedicated DDR Memory Support**
  - Implements interface up to DDR333 (166MHz)
- **sysCLOCK™ PLLs**
  - Up to 4 analog PLLs per device
  - Clock multiply, divide and phase shifting
- **System Level Support**
  - IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
  - Onboard oscillator for configuration
  - Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply

Table 1-1. LatticeXP Family Selection Guide

Device	LFXP3	LFXP6	LFXP10	LFXP15	LFXP20
PFU/PFF Rows	16	24	32	40	44
PFU/PFF Columns	24	30	38	48	56
PFU/PFF (Total)	384	720	1216	1932	2464
LUTs (K)	3	6	10	15	20
Distributed RAM (KBits)	12	23	39	61	79
EBR SRAM (KBits)	54	72	216	324	396
EBR SRAM Blocks	6	8	24	36	44
V_{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
PLLs	2	2	4	4	4
Max. I/O	136	188	244	300	340
Packages and I/O Combinations:					
100-pin TQFP (14 x 14 mm)	62				
144-pin TQFP (20 x 20 mm)	100	100			
208-pin PQFP (28 x 28 mm)	136	142			
256-ball fpBGA (17 x 17 mm)		188	188	188	188
388-ball fpBGA (23 x 23 mm)			244	268	268
484-ball fpBGA (23 x 23 mm)				300	340

Table 2-1. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCIN	Fast Carry In[1]
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	For the right most PFU the fast carry chain output[1]

1. See Figure 2-2 for connection details.
2. Requires two PFUs.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Two additional signals: Carry Generate and Carry Propagate are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM[1]	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

Routing

There are many resources provided in the LatticeXP devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. The x2 and x6 resources are buffered allowing both short and long connections routing between PFUs.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeXP devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeXP devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-5 shows the 20 primary clock sources.

Figure 2-18. Group of Seven PIOs

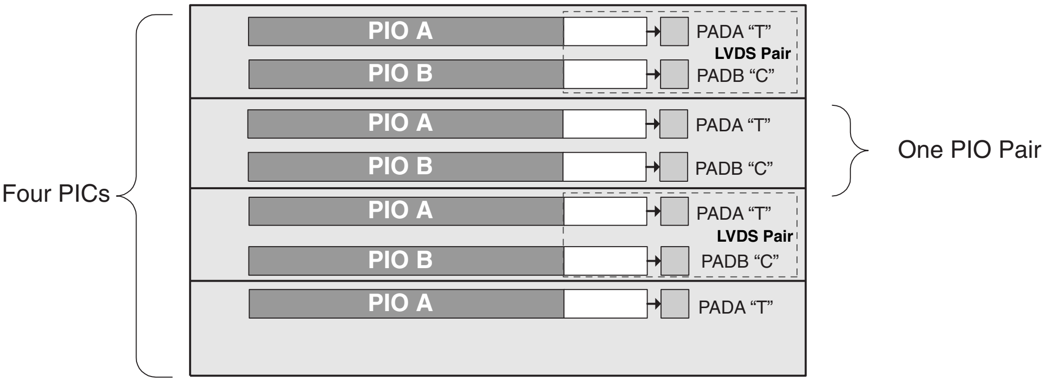
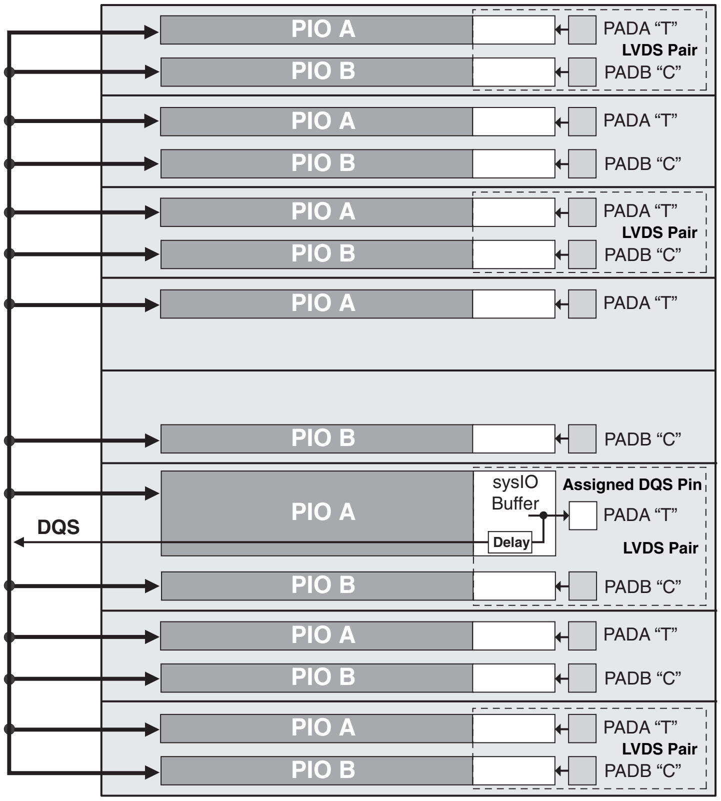


Figure 2-19. DQS Routing



PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for both single data rate (SDR) and double data rate (DDR) operation along with the necessary clock and selection logic. Programmable delay lines used to shift incoming clock and data signals are also included in these blocks.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-20 shows the diagram of the input register block.

Input signals are fed from the sysIO buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and

Table 2-9. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <100mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	Off	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up typically in the order of 10µA along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to V_{CC} is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically the device enters Sleep Mode several hundred ns after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet show a detailed timing diagram.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeXP family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeXP devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeXP devices contain two possible ports that can be used for device configuration and programming. The test access port (TAP), which supports serial configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The non-volatile memory in the LatticeXP can be configured in three different modes:

- In sysCONFIG mode via the sysCONFIG port. Note this can also be done in background mode.
- In 1532 mode via the 1149.1 port.
- In background mode via the 1149.1 port. This allows the device to be operated while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- In 1532 mode via the 1149.1 port SRAM direct configuration.
- In sysCONFIG mode via the sysCONFIG port SRAM direct configuration.

master serial clock is 2.5MHz. Table 2-10 lists all the available Master Serial Clock frequencies. When a different Master Serial Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Serial Clock frequency for configuration.
2. During configuration the device starts with the default (2.5MHz) Master Serial Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Serial Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information on the use of this oscillator for configuration, please see details of additional technical documentation at the end of this data sheet.

Table 2-10. Selectable Master Serial Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5[1]	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

1. Default

Density Shifting

The LatticeXP family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LFXP3E	15	mA
		LFXP6E	20	mA
		LFXP10E	35	mA
		LFXP15E	45	mA
		LFXP20E	55	mA
		LFXP3C	35	mA
		LFXP6C	40	mA
		LFXP10C	70	mA
		LFXP15C	80	mA
		LFXP20C	90	mA
I_{CCP}	PLL Power Supply (per PLL)	All	8	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	22	mA
		LFXP6E/C	22	mA
		LFXP10E/C	30	mA
		LFXP15E/C	30	mA
		LFXP20E/C	30	mA
I_{CCIO}	Bank Power Supply[6]	All	2	mA
I_{CCJ}	V_{CCJ} Power Supply	All	1	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the VCCIO or GND.
3. Frequency 0MHz.
4. User pattern: blank.
5. T_A=25°C, power supplies at nominal voltage.
6. Per bank.

sysIO Recommended Operating Conditions

	V_{CCIO}			V_{REF} (V)		
Standard	**Min.**	**Typ.**	**Max.**	**Min.**	**Typ.**	**Max.**
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI33	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—

[1] Inputs on chip. Outputs are implemented with the addition of external resistors.

Typical Building Block Function Performance[1]

Pin-to-Pin Performance (LVCMOS25 12 mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.1	ns
32-bit decoder	7.3	ns
64-bit decoder	8.2	ns
4:1 MUX	4.9	ns
8:1 MUX	5.3	ns
16:1 MUX	5.7	ns
32:1 MUX	6.3	ns

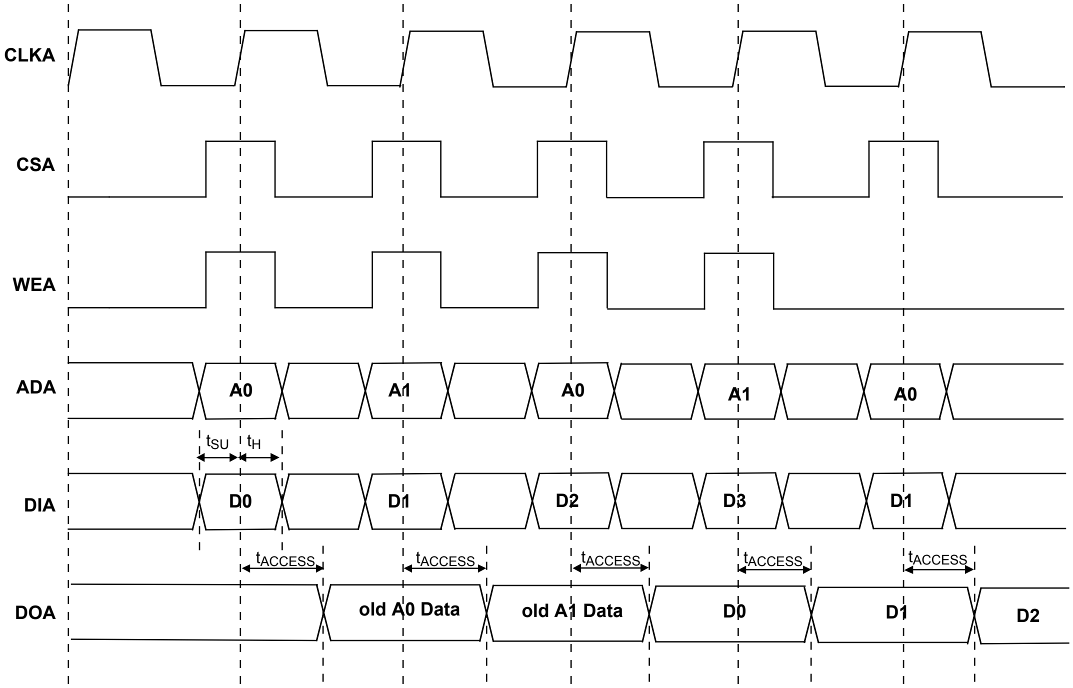
Register to Register Performance

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	351	MHz
32-bit decoder	248	MHz
64-bit decoder	237	MHz
4:1 MUX	590	MHz
8:1 MUX	523	MHz
16:1 MUX	434	MHz
32:1 MUX	355	MHz
8-bit adder	343	MHz
16-bit adder	292	MHz
64-bit adder	130	MHz
16-bit counter	388	MHz
32-bit counter	295	MHz
64-bit counter	200	MHz
64-bit accumulator	164	MHz
Embedded Memory Functions		
Single Port RAM 256x36 bits	254	MHz
True-Dual Port RAM 512x18 bits	254	MHz
Distributed Memory Functions		
16x2 SP RAM	434	MHz
64x2 SP RAM	332	MHz
128x4 SP RAM	235	MHz
32x2 PDP RAM	322	MHz
64x4 PDP RAM	291	MHz

1. These timing numbers were generated using the ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

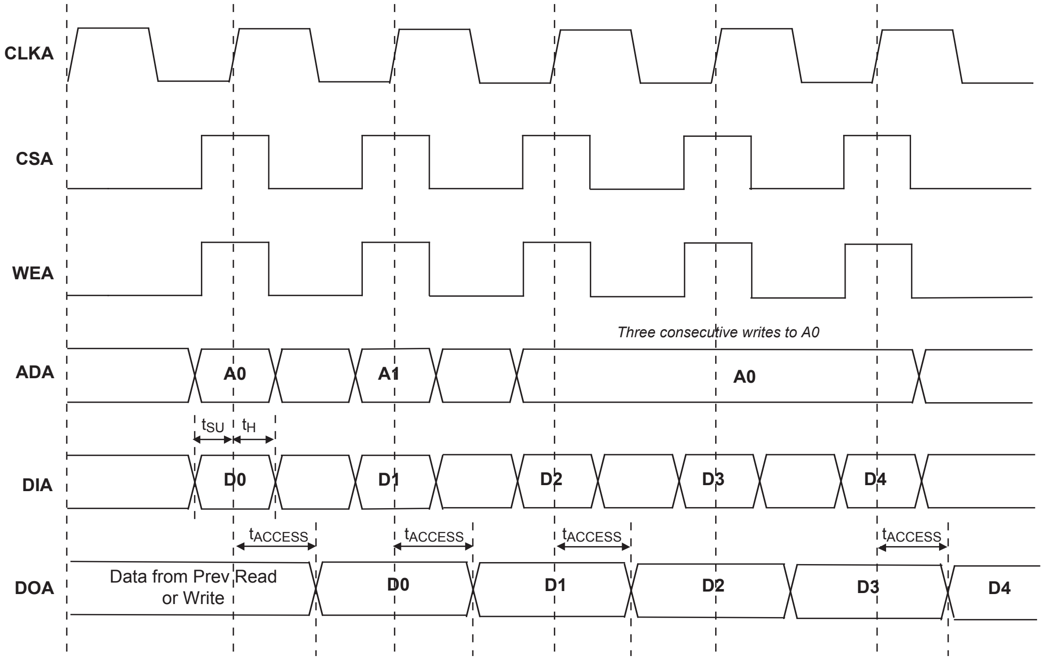
Timing v.F0.11

Figure 3-10. Read Before Write (SP Read/Write on Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-11. Write Through (SP Read/Write On Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

LatticeXP Family Timing Adders[1]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.5	0.5	0.5	ns
LVDS25	LVDS	0.4	0.4	0.4	ns
BLVDS25	BLVDS	0.5	0.5	0.5	ns
LVPECL33	LVPECL	0.6	0.6	0.6	ns
HSTL18_I	HSTL_18 class I	0.4	0.4	0.4	ns
HSTL18_II	HSTL_18 class II	0.4	0.4	0.4	ns
HSTL18_III	HSTL_18 class III	0.4	0.4	0.4	ns
HSTL18D_I	Differential HSTL 18 class I	0.4	0.4	0.4	ns
HSTL18D_II	Differential HSTL 18 class II	0.4	0.4	0.4	ns
HSTL18D_III	Differential HSTL 18 class III	0.4	0.4	0.4	ns
HSTL15_I	HSTL_15 class I	0.5	0.5	0.5	ns
HSTL15_III	HSTL_15 class III	0.5	0.5	0.5	ns
HSTL15D_I	Differential HSTL 15 class I	0.5	0.5	0.5	ns
HSTL15D_III	Differential HSTL 15 class III	0.5	0.5	0.5	ns
SSTL33_I	SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33_II	SSTL_3 class II	0.6	0.6	0.6	ns
SSTL33D_I	Differential SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33D_II	Differential SSTL_3 class II	0.6	0.6	0.6	ns
SSTL25_I	SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25_II	SSTL_2 class II	0.5	0.5	0.5	ns
SSTL25D_I	Differential SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25D_II	Differential SSTL_2 class II	0.5	0.5	0.5	ns
SSTL18_I	SSTL_18 class I	0.5	0.5	0.5	ns
SSTL18D_I	Differential SSTL_18 class I	0.5	0.5	0.5	ns
LVTTL33	LVTTL	0.2	0.2	0.2	ns
LVCMOS33	LVCMOS 3.3	0.2	0.2	0.2	ns
LVCMOS25	LVCMOS 2.5	0.0	0.0	0.0	ns
LVCMOS18	LVCMOS 1.8	0.1	0.1	0.1	ns
LVCMOS15	LVCMOS 1.5	0.1	0.1	0.1	ns
LVCMOS12	LVCMOS 1.2	0.1	0.1	0.1	ns
PCI33	PCI	0.2	0.2	0.2	ns
Output Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.3	0.3	0.3	ns
LVDS25	LVDS 2.5	0.3	0.3	0.3	ns
BLVDS25	BLVDS 2.5	0.3	0.3	0.3	ns
LVPECL33	LVPECL 3.3	0.1	0.1	0.1	ns
HSTL18_I	HSTL_18 class I	0.1	0.1	0.1	ns
HSTL18_II	HSTL_18 class II	0.1	0.1	0.1	ns
HSTL18_III	HSTL_18 class III	0.2	0.2	0.2	ns
HSTL18D_I	Differential HSTL 18 class I	0.1	0.1	0.1	ns
HSTL18D_II	Differential HSTL 18 class II	-0.1	-0.1	-0.1	ns
HSTL18D_III	Differential HSTL 18 class III	0.2	0.2	0.2	ns

LatticeXP Family Timing Adders[1] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTL33_4mA	LVTTL 4mA drive	0.8	0.8	0.8	ns
LVTTL33_8mA	LVTTL 8mA drive	0.5	0.5	0.5	ns
LVTTL33_12mA	LVTTL 12mA drive	0.3	0.3	0.3	ns
LVTTL33_16mA	LVTTL 16mA drive	0.4	0.4	0.4	ns
LVTTL33_20mA	LVTTL 20mA drive	0.3	0.3	0.3	ns
LVCMOS33_2mA	LVCMOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVCMOS25_2mA	LVCMOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVCMOS18_2mA	LVCMOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVCMOS15_2mA	LVCMOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

[1] General timing numbers based on LVCMOS 2.5, 12mA.

Timing v.F0.11

LFXP3 Logic Signal Connections: 100 TQFP

Pin Number	Pin Function	Bank	Differential	Dual Function
1	CFG1	0	-	-
2	DONE	0	-	-
3	PROGRAMN	7	-	-
4	CCLK	7	-	-
5	PL3A	7	T	LUM0_PLLT_FB_A
6	PL3B	7	C	LUM0_PLLC_FB_A
7	VCCIO7	7	-	-
8	PL5A	7	-	VREF1_7
9	PL6B	7	-	VREF2_7
10	GNDIO7	7	-	-
11	PL7A	7	T[3]	DQS
12	PL7B	7	C[3]	-
13	PL8A	7	T	LUM0_PLLT_IN_A
14	PL8B	7	C	LUM0_PLLC_IN_A
15	PL9A	7	T[3]	-
16	PL9B	7	C[3]	-
17	VCCP0	-	-	-
18	GNDP0	-	-	-
19	PL12A	6	T	PCLKT6_0
20	PL12B	6	C	PCLKC6_0
21	GNDIO6	6	-	-
22	VCCIO6	6	-	-
23	PL18A	6	T[3]	-
24	PL18B	6	C[3]	-
25	VCCAUX	-	-	-
26	SLEEPN[1]/TOE[2]	-	-	-
27	INITN	5	-	-
28	VCC	-	-	-
29	PB2B	5	-	VREF1_5
30	PB5B	5	-	VREF2_5
31	PB8A	5	T	-
32	PB8B	5	C	-
33	GNDIO5	5	-	-
34	PB9A	5	-	-
35	PB10B	5	-	-
36	PB11A	5	T	DQS
37	PB11B	5	C	-
38	VCCIO5	5	-	-
39	PB12A	5	T	-
40	PB12B	5	C	-
41	PB13A	5	T	-
42	PB13B	5	C	-
43	GND	-	-	-

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
93	PR9A	2	T	PCLKT2_0	PR12A	2	T	PCLKT2_0
94	PR8B	2	C	RUM0_PLLC_IN_A	PR8B	2	C	RUM0_PLLC_IN_A
95	PR8A	2	T	RUM0_PLLT_IN_A	PR8A	2	T	RUM0_PLLT_IN_A
96	PR7B	2	C[3]	-	PR7B	2	C[3]	-
97	PR7A	2	T[3]	DQS	PR7A	2	T[3]	DQS
98	VCCIO2	2	-	-	VCCIO2	2	-	-
99	PR6B	2	-	VREF1_2	PR6B	2	-	VREF1_2
100	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
101	GNDIO2	2	-	-	GNDIO2	2	-	-
102	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
103	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A
104	PR2B	2	C[3]	-	PR2B	2	C[3]	-
105	PR2A	2	T[3]	-	PR2A	2	T[3]	-
106	VCCAUX	-	-	-	VCCAUX	-	-	-
107	TDO	-	-	-	TDO	-	-	-
108	VCCJ	-	-	-	VCCJ	-	-	-
109	TDI	-	-	-	TDI	-	-	-
110	TMS	-	-	-	TMS	-	-	-
111	TCK	-	-	-	TCK	-	-	-
112	VCC	-	-	-	VCC	-	-	-
113	PT25A	1	-	VREF1_1	PT28A	1	-	VREF1_1
114	PT24A	1	-	-	PT27A	1	-	-
115	PT23A	1	-	D0	PT26A	1	-	D0
116	PT22B	1	C	D1	PT25B	1	C	D1
117	PT22A	1	T	VREF2_1	PT25A	1	T	VREF2_1
118	PT21A	1	-	D2	PT24A	1	-	D2
119	VCCIO1	1	-	-	VCCIO1	1	-	-
120	PT20B	1	-	D3	PT23B	1	-	D3
121	GNDIO1	1	-	-	GNDIO1	1	-	-
122	PT17A	1	-	D4	PT20A	1	-	D4
123	PT16A	1	-	D5	PT19A	1	-	D5
124	PT15B	1	C	D6	PT18B	1	C	D6
125	PT15A	1	T	-	PT18A	1	T	-
126	PT14B	1	-	D7	PT17B	1	-	D7
127	GND	-	-	-	GND	-	-	-
128	PT13B	0	C	BUSY	PT16B	0	C	BUSY
129	PT13A	0	T	CS1N	PT16A	0	T	CS1N
130	PT12B	0	C	PCLKC0_0	PT15B	0	C	PCLKC0_0
131	PT12A	0	T	PCLKT0_0	PT15A	0	T	PCLKT0_0
132	PT11B	0	C	-	PT14B	0	C	-
133	VCCIO0	0	-	-	VCCIO0	0	-	-
134	PT11A	0	T	DQS	PT14A	0	T	DQS
135	PT9A	0	-	DOUT	PT12A	0	-	DOUT
136	GNDIO0	0	-	-	GNDIO0	0	-	-
137	PT8A	0	-	WRITEN	PT11A	0	-	WRITEN
138	PT7A	0	-	VREF1_0	PT10A	0	-	VREF1_0

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
F4	PROGRAMN	7	-	-	PROGRAMN	7	-	-	PROGRAMN	7	-	-
G4	CCLK	7	-	-	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL2A	7	T[3]	-	PL6A	7	T[3]	-	PL6A	7	T[3]	-
D1	PL2B	7	C[3]	-	PL6B	7	C[3]	-	PL6B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
E2	PL3A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
E3	PL3B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
F3	PL4A	7	T[3]	-	PL8A	7	T[3]	-	PL8A	7	T[3]	-
F2	PL4B	7	C[3]	-	PL8B	7	C[3]	-	PL8B	7	C[3]	-
H4	PL5A	7	-	-	PL9A	7	-	-	PL9A	7	-	-
H3	PL6B	7	-	VREF1_7	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
G3	PL7A	7	T[3]	DQS	PL11A	7	T[3]	DQS	PL11A	7	T[3]	DQS
G2	PL7B	7	C[3]	-	PL11B	7	C[3]	-	PL11B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
F1	PL8A	7	T	-	PL12A	7	T	-	PL12A	7	T	-
E1	PL8B	7	C	-	PL12B	7	C	-	PL12B	7	C	-
J4	PL9A	7	T[3]	-	PL13A	7	T[3]	-	PL13A	7	T[3]	-
K4	PL9B	7	C[3]	-	PL13B	7	C[3]	-	PL13B	7	C[3]	-
G1	PL11A	7	T[3]	-	PL15A	7	T[3]	-	PL15A	7	T[3]	-
H2	PL11B	7	C[3]	-	PL15B	7	C[3]	-	PL15B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
J2	PL12A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
H1	PL12B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
J1	PL13A	7	T[3]	-	PL17A	7	T[3]	-	PL17A	7	T[3]	-
K2	PL13B	7	C[3]	-	PL17B	7	C[3]	-	PL17B	7	C[3]	-
K3	PL14A	7	-	VREF2_7	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
J3	PL15B	7	-	-	PL19B	7	-	-	PL19B	7	-	-
K1	PL16A	7	T[3]	DQS	PL20A	7	T[3]	DQS	PL20A	7	T[3]	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-	GNDIO7	7	-	-
L2	PL16B	7	C[3]	-	PL20B	7	C[3]	-	PL20B	7	C[3]	-
L3	PL17A	7	T	-	PL21A	7	T	-	PL21A	7	T	-
L4	PL17B	7	C	-	PL21B	7	C	-	PL21B	7	C	-
L1	PL18A	7	T[3]	-	PL22A	7	T[3]	-	PL22A	7	T[3]	-
M1	PL18B	7	C[3]	-	PL22B	7	C[3]	-	PL22B	7	C[3]	-
M2	VCCP0	-	-	-	VCCP0	-	-	-	VCCP0	-	-	-
N1	GNDP0	-	-	-	GNDP0	-	-	-	GNDP0	-	-	-
M3	PL19A	6	T[3]	-	PL23A	6	T[3]	-	PL27A	6	T[3]	-
M4	PL19B	6	C[3]	-	PL23B	6	C[3]	-	PL27B	6	C[3]	-
P1	PL20A	6	T	PCLKT6_0	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
N2	PL20B	6	C	PCLKC6_0	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
R1	PL21A	6	T[3]	-	PL25A	6	T[3]	-	PL29A	6	T[3]	-
P2	PL21B	6	C[3]	-	PL25B	6	C[3]	-	PL29B	6	C[3]	-
N3	PL22A	6	-	-	PL26A	6	-	-	PL30A	6	-	-
N4	PL23B	6	-	VREF1_6	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T1	PL24A	6	T[3]	DQS	PL28A	6	T[3]	DQS	PL32A	6	T[3]	DQS
R2	PL24B	6	C[3]	-	PL28B	6	C[3]	-	PL32B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
A7	PT13A	0	T	DI	PT18A	0	T	DI	PT22A	0	T	DI
B7	PT12B	0	C	-	PT17B	0	C	-	PT21B	0	C	-
C6	PT12A	0	T	CSN	PT17A	0	T	CSN	PT21A	0	T	CSN
C10	PT11B	0	C	-	PT16B	0	C	-	PT20B	0	C	-
C9	PT11A	0	T	-	PT16A	0	T	-	PT20A	0	T	-
A6	PT10B	0	C	VREF2_0	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
B6	PT10A	0	T	DQS	PT15A	0	T	DQS	PT19A	0	T	DQS
A5	PT9B	0	-	-	PT14B	0	-	-	PT18B	0	-	-
B5	PT8A	0	-	-	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C5	PT7B	0	C	-	PT12B	0	C	-	PT16B	0	C	-
A4	PT7A	0	T	-	PT12A	0	T	-	PT16A	0	T	-
D9	PT6B	0	C	-	PT11B	0	C	-	PT15B	0	C	-
D8	PT6A	0	T	-	PT11A	0	T	-	PT15A	0	T	-
B4	PT5B	0	C	-	PT10B	0	C	-	PT14B	0	C	-
A2	PT5A	0	T	-	PT10A	0	T	-	PT14A	0	T	-
A3	PT4B	0	C	-	PT9B	0	C	-	PT13B	0	C	-
B3	PT4A	0	T	-	PT9A	0	T	-	PT13A	0	T	-
C4	PT3B	0	C	-	PT8B	0	C	-	PT12B	0	C	-
C3	PT3A	0	T	-	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C2	-	-	-	-	PT7B	0	C	-	PT11B	0	C	-
D3	PT2A	0	-	-	PT7A	0	T	DQS	PT11A	0	T	DQS
D7	-	-	-	-	PT6B	0	-	-	PT10B	0	-	-
D6	-	-	-	-	PT5A	0	-	-	PT9A	0	-	-
E4	-	-	-	-	PT4B	0	C	-	PT8B	0	C	-
D4	-	-	-	-	PT4A	0	T	-	PT8A	0	T	-
D5	-	-	-	-	PT3B	0	-	-	PT7B	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C1	CFG0	0	-	-	CFG0	0	-	-	CFG0	0	-	-
B2	CFG1	0	-	-	CFG1	0	-	-	CFG1	0	-	-
B1	DONE	0	-	-	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-	GND	-	-	-
H11	GND	-	-	-	GND	-	-	-	GND	-	-	-
H12	GND	-	-	-	GND	-	-	-	GND	-	-	-
H13	GND	-	-	-	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-	GND	-	-	-

Conventional Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208C	136	1.8/2.5/3.3V	-3	PQFP	208	COM	3.1K
LFXP3C-4Q208C	136	1.8/2.5/3.3V	-4	PQFP	208	COM	3.1K
LFXP3C-5Q208C	136	1.8/2.5/3.3V	-5	PQFP	208	COM	3.1K
LFXP3C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	3.1K
LFXP3C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	3.1K
LFXP3C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	3.1K
LFXP3C-3T100C	62	1.8/2.5/3.3V	-3	TQFP	100	COM	3.1K
LFXP3C-4T100C	62	1.8/2.5/3.3V	-4	TQFP	100	COM	3.1K
LFXP3C-5T100C	62	1.8/2.5/3.3V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	5.8K
LFXP6C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	5.8K
LFXP6C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	5.8K
LFXP6C-3Q208C	142	1.8/2.5/3.3V	-3	PQFP	208	COM	5.8K
LFXP6C-4Q208C	142	1.8/2.5/3.3V	-4	PQFP	208	COM	5.8K
LFXP6C-5Q208C	142	1.8/2.5/3.3V	-5	PQFP	208	COM	5.8K
LFXP6C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	5.8K
LFXP6C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	5.8K
LFXP6C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388C	244	1.8/2.5/3.3V	-3	fpBGA	388	COM	9.7K
LFXP10C-4F388C	244	1.8/2.5/3.3V	-4	fpBGA	388	COM	9.7K
LFXP10C-5F388C	244	1.8/2.5/3.3V	-5	fpBGA	388	COM	9.7K
LFXP10C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	9.7K
LFXP10C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	9.7K
LFXP10C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	9.7K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3FN388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4FN388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3FN484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4FN484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4FN484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4QN208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3TN144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4TN144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3TN100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4TN100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4FN256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3QN208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4QN208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3TN144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4TN144I	100	1.2V	-4	TQFP	144	IND	5.8K

LatticeXP Family Data Sheet
Revision History

November 2007 **Data Sheet DS1001**

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
		DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
			Updated Logic Signal Connections Dual Function column.
		Ordering Information	Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
			Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
September 2005	03.0	Architecture	Added clarification of PCI clamp.
			Added clarification to SLEEPN Pin Characteristics section.
		DC and Switching Characteristics	DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.